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(75) Inventors/Applicants (for US only): ITOH, Yuji [JP/JP];
c/o Corporate R & D Center, SHOWA DENKO K.K., 1-1,
Ohnodai 1-chome, Midori-ku, Chiba-shi, Chiba 2670056
(JP). NISHIOKA, Ayako [JP/JP]; c/o Corporate R & D
Center, SHOWA DENKO K.K., 1-1, Ohnodai 1-chome,
Midori-ku, Chiba-shi, Chiba 2670056 (JP). UOTANI,
Nobuo [JP/JP]; c/o Shiojiri Plant, SHOWA DENKO K.K.,
1, Oaza Soga, Shiojiri-shi, Nagano 3996461 (JP).

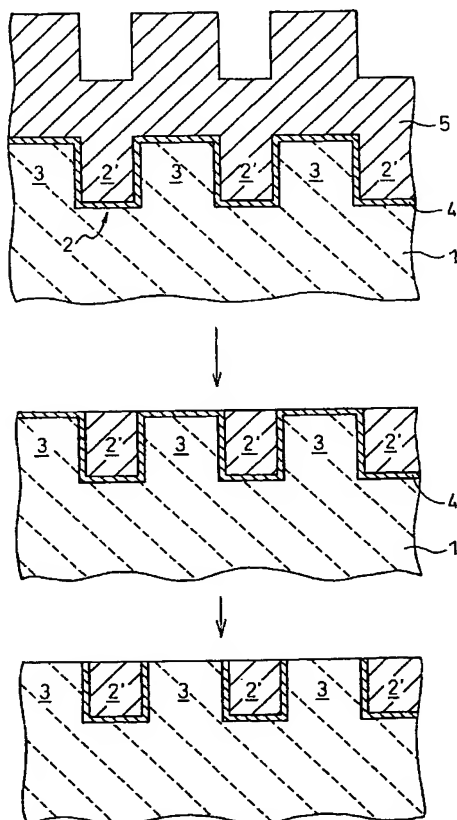
(74) Agents: AOKI, Atsushi et al.; A. AOKI, ISHIDA & AS-
SOCIATES, Toranomon 37 Mori Bldg., 5-1, Toranomon
3-chome, Minato-ku, Tokyo 1058423 (JP).

(71) Applicant (for all designated States except US): SHOWA
DENKO K.K. [JP/JP]; 13-9, Shibadaimon 1-chome, Mi-
nato-ku, Tokyo 1058518 (JP).

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(54) Title: POLISHING COMPOSITION AND POLISHING METHOD



(57) Abstract: As a polishing composition which allows high-speed polish-
ing while dishing and erosion are prevented and the flatness of metal film is
maintained, there is provided a polishing composition for polishing a metal
film provided on a substrate having trenches such that the metal film fills
the trenches, so as to provide a planarized surface, wherein the composition
comprises water, a phosphate ester having a C ≥ 6 carbon atom alkyl group
in its molecule, and an etchant for the metal, and has a pH of 5 to 11.



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